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| <b><u>Title:</u></b>               | <i>FIB for Semiconductor Failure Analysis application</i>  |
| <b><u>Training duration:</u></b>   | <i>3 days</i>  |
| <b><u>Training cost:</u></b>       | <i>Groups of 1 – 5 trainees, US\$3600 per group</i>  |
| <b><u>Background required:</u></b> | <i>Basic FIB operator training, or equivalent</i>  |
| <b><u>Student Objective:</u></b>   | <i>Know defect localization techniques, make, image, and analyze FIB cross-sections of semiconductor devices, apply voltage contrast methods</i> |
| <b><u>Equipment:</u></b>           | <i>Micrion 2000, 2500, 9000, 9100, 986, 986FC, Vectra 986(+), VectraVision,</i>  |
| <b><u>Syllabus:</u></b>            | <i>Available online: <a href="http://www.partbeamsystech.com/training.html">www.partbeamsystech.com/training.html</a></i>                        |